

SOT144-1

plastic micro flat package; 8 leads (straight)

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	PMFP8
Package type industry code	PMFP8
Package style descriptive code	PMFP (plastic micro flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	12-3-2003

Table 1. Package summary

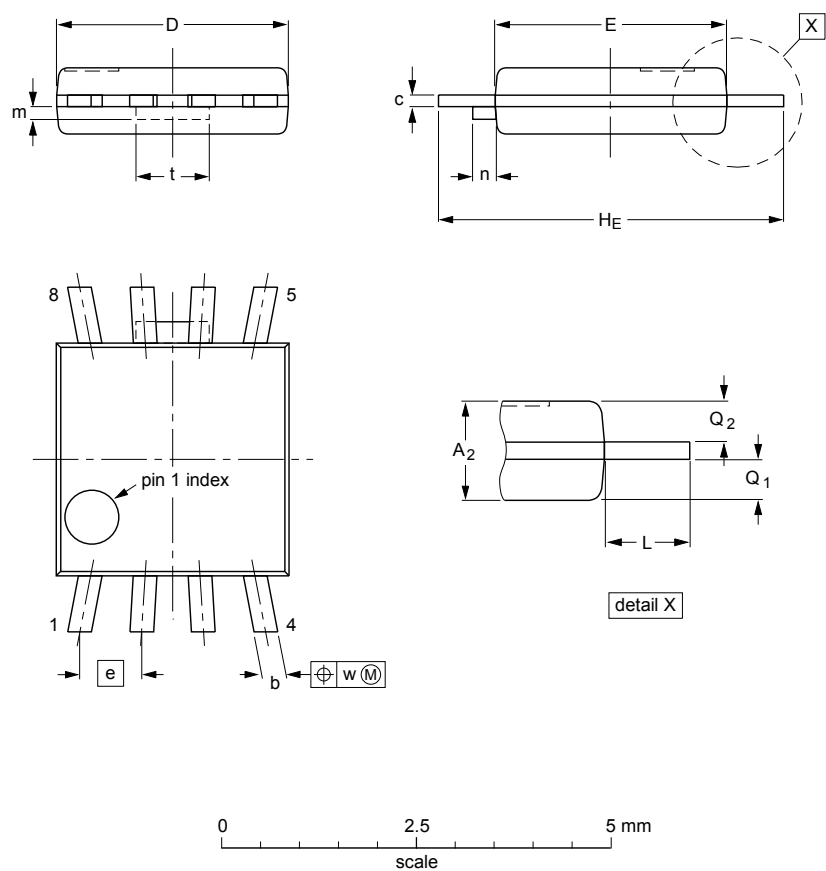
Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		2.9	-	3	3.1	mm
E	package width		2.9	-	3	3.1	mm
A ₂	package height		0.7	-	0.83	0.9	mm
n ₂	actual quantity of termination		-	-	8	-	



2. Package outline

PMFP8: plastic micro flat package; 8 leads (straight)

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DIMENSIONS (mm are the original dimensions)

UNIT	A ₂	b	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	m _{max.}	n _{max.}	Q ₁	Q ₂	t	w
mm	0.9 0.7	0.40 0.25	0.19 0.12	3.1 2.9	3.1 2.9	0.8	4.6 4.4	0.75	0.26	0.3	0.4 0.3	0.4 0.3	0.95	0.1

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT144-1						95-01-24 03-03-12

Fig. 1. Package outline PMFP8 (SOT144-1)

3. Legal information

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Date of release: 8 February 2016